

CONFERENCES IN 2008:

IEEE Workshop on **Signal Propagation on Interconnects** (SPI 2008) www.univ-brest.fr/SPI
May 12-15, 2008 Avignon, France
Contact: Denis Deschacht, Denis.Deschacht@lirmm.fr

58th **Electronic Components and Technology Conference** (ECTC 2008) www.ectc.net
May 27 - 30, 2008; Disney's Contemporary Resort
Lake Buena Vista, Florida USA
Contact: Jean Trehwella, IBM, jeanmh@us.ibm.com

Intersociety Conference on **Thermal and Thermomechanical Phenomena in Electronic Systems** (I-THERM 2008) www.ithermconference.org
May 28-31, 2008 Orlando, FL USA
Contact: Ms. Kelly Sutton, epd@enr.arizona.edu

18th IEEE **Semiconductor Wafer Test Workshop** (SWTW 2008) www.swtest.org
June 8-11, 2008 San Diego, CA USA
Contact: Bill Mann, william.mann@ieee.org

International **Conference on Electronics Packaging** (ICEP 2008) www.jiep.or.jp/icep
June 10-12, 2008 Tokyo Big Sight, Tokyo, Japan
Contact: ICEP Secretariat at icep@jiep.or.jp

Joint Int'l Conference on **Electronic Packaging Technology & High Density Packaging** (ICEPT-HDP) www.icept.org
July 28-31, 2008 Shanghai, China
CFP Abstracts Deadline: April 11, 2008
Contact: ICEPT-HDP Secretariat at icept2008@fudan.edu.cn

Joint Event: 7th Int'l IEEE Conference on **Polymers and Adhesives in Microelectronics and Photonics** (POLYTRONIC 2008) with **PORTABLE 2008**
August 17-22, 2008 Edelweiss Hotel & Conference Center
www.polytronic2008.com
Garmisch-Partenkirchen, Germany
Contact: info@polytronic2008.com

Electronics System-Integration Technology Conference (ESTC 2008) www.estc.biz
September 1-4, 2008; University of Greenwich
Greenwich, London UK
Contact: Chris Bailey, Greenwich University,
chris.bailey@estc.biz

2008 Workshop on **Accelerated Stress Testing & Reliability** (ASTR) www.ewh.ieee.org/soc/cpmt/tc7/ast2008
October 1 - 3, 2008 Portland, OR USA
Abstracts Due: April 28, 2008
Contact: Cheryl Tulkoff, National Instruments,
cheryl.tulkoff@ni.com

Joint Event: 3rd **Int'l Microsystems, Packaging, Assembly and Circuits Technology** (IMPACT) Conference, with the 10th Int'l Conference on **Electronics Materials and Packaging** (EMAP) www.impact-emap.org
October 22 - 24, 2008 Taipei, Taiwan
Abstracts Due: May 31, 2008
Contact: Mr. Long-Shien Lin, tw2008@isu.edu.tw

54th IEEE **Holm Conference on Electrical Contacts** (HOLM 2008) www.ewh.ieee.org/soc/cpmt/tc1/h2008/h2008top.html
27-29 October, 2008 Orlando, FL USA
Contact: Chi H. Leung, AMID DODUCO,
cleung@amidoduco.com

33rd Int'l **Electronics Manufacturing Technology Symposium** (IEMT 2008) www.cpmt.ieemalaysia.org
November 4-6, 2008; Penang, Malaysia
Contact: Ir. Dr. Cheong Kuan Yew, USM
cheong@eng.usm.my

9th **VLSI Packaging Workshop in Japan**
December 1 - 2, 2008; Kyoto, Japan vlsi-pkg-ws.org
Abstracts Due: May 31, 2008
Contact: Michitaka Kimura, Renesas Technology Corp,
kimura.michitaka@renesas.com

10th **Electronics Packaging Technology Conference** (EPTC 2008) www.eptc-ieee.net
December 9-12, 2008; Singapore
Abstracts due June 10, 2008
Contact: Dr. Tong Yan Tee, tytee@amkor.com

Electrical Design of Advanced Packaging and Systems (EDAPS 2008) www.edaps2008.org
December 10-12, 2008 COEX Conference Center
Seoul, Korea
Papers due: July 31, 2008
Contact: S.M Yang, yangsm@ee.kaist.ac.kr (Office: 82-42-869-5458)

2nd Int'l Conference on **Thermal issues in Emerging Technologies, Theory and Applications** (ThETA2)
December 17-20, 2008 Cairo, Egypt www.thetaconf.org
Papers due: July 31, 2008
Contact: thetaconf@gmail.com

CONFERENCES IN 2009:

European Microelectronics and Packaging Conference & Exhibition (EMPC 2009) www.empc2009.org
June 14-17, 2009 Rimini, Italy
Abstracts due: December 31, 2008
Contact: Pragma Congressi, segreteria@empc2009.org